

Amendment and Response

Applicant: Steiner et al.

Serial No.: 10/519,215

Filed: September 19, 2005

Docket No.: 431.122.101/FIN399PCT/US

Title: ELECTRONIC COMPONENT WITH A HOUSING PACKAGE

IN THE CLAIMS

Please cancel claims 32-48, 50, 52, and 55-60.

Please amend claims 31, 49, 51, 53 and 54 as follows:

1-30. (Cancelled)

31. (Currently Amended) An electronic component comprising:
a housing package comprising a plurality of layers of plastic;
at least one buried interconnect layer; and
at least one semiconductor chip, which has pointed-conical external contacts distributed
on an outer side, the pointed-conical external contacts penetrating through one of the layers of
plastic in the housing package and forming contact vias to the buried interconnect layer,
wherein an underside of the semiconductor chip and the pointed-conical external contacts
are surrounded by one of the layers of plastic;
wherein the pointed-conical external contacts maintain a pointed-conical configuration
within the layers of plastic.

32-48. (Cancelled)

49. (Currently Amended) The electronic component panel of claim 3145, comprising
wherein the electronic component panel has external contact areas in each component position
on the underside and/or the upper side.

50. (Cancelled)

51. (Currently Amended) The electronic component panel of claim 3145, comprising
wherein the electronic component panel has passive components on its upper side, the

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components being connected by means of contact vias in the uppermost layer of plastic to one of the buried interconnect layers.

52. (Cancelled)

53. (Currently Amended) The electronic component panel of claim 3145, comprising wherein the electronic component panel has at least one layer of plastic of a pre-crosslinked plastic.

54. (Currently Amended) The electronic component panel of claim 3145, comprising wherein the electronic component panel has at least one layer of plastic with glass fiber or carbon fiber reinforcements.

55- 60. (Cancelled)